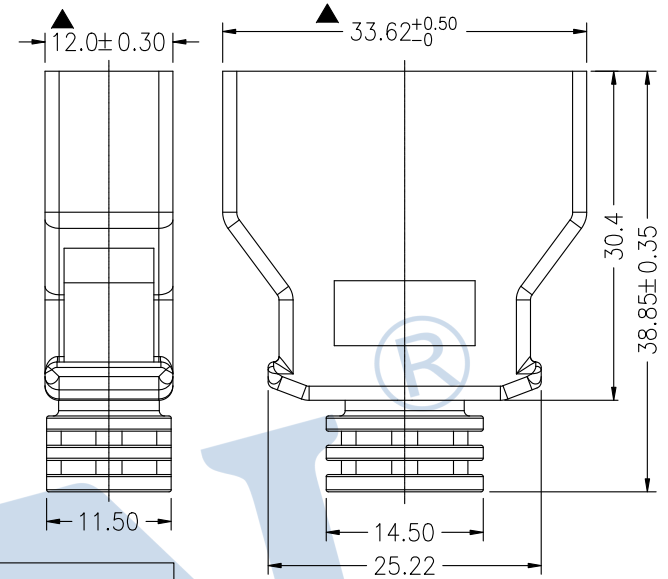
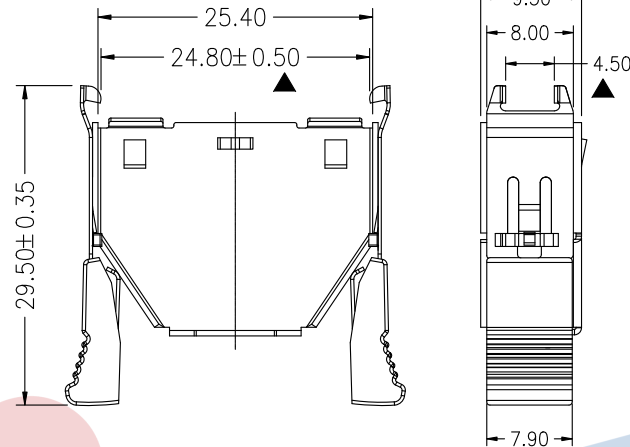
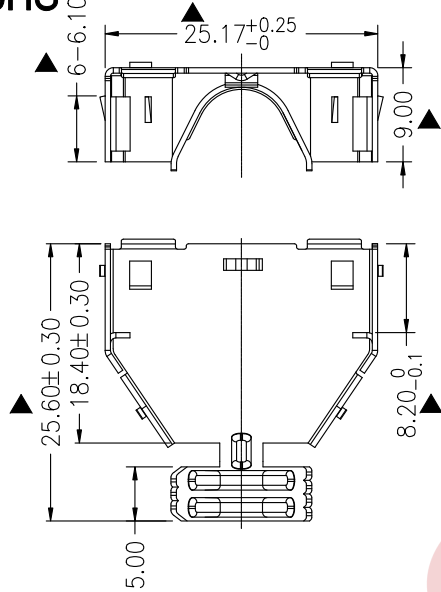


**HSF RoHS**

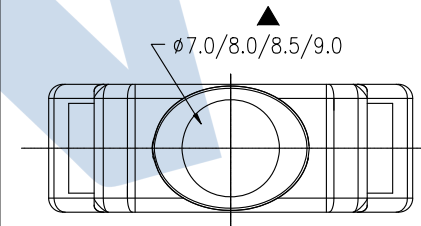
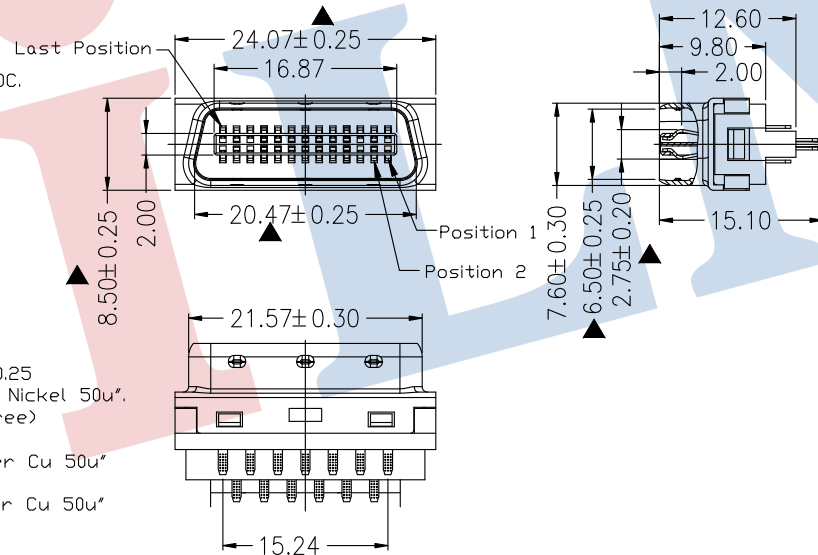


**Specification:**

- 1.Contact Resistance: 35 m Ohm Max.
- 2.Insulation Resistance: 200 M Ohm Min. At 500V DC.
- 3.Contact Current Rating: 1 Amp AC/DC
- 3.Voltage Rating: 40V AC.
- 4.Withstanding Voltage: 500V AC For 1 Minute.
- 5.Operating Temperature: -25°C to +85°C
- 6.Packing: Tray
- 7.Control Dimensions Indicated From "▲".

**Material and Finish:**

- 1.Insulator Material: PBTUL94-V0,Black
- 2.Cover Material: PBTUL94-V0,Black
- 3.Hood Plastic Material: ABS,Black
- 4.Bullon Plastic Material: ABS,Black
- 5.Contact Material: Phosphor Bronze(C5191-EH)T=0.25
- 6.Contact Area Plated: Gold 1~30u" Plated Over Nickel 50u"
- 7.Solder Area Plated: Tin Plated(80u" min Lead Free)
- 8.Up or Down Shell Material: SPCC T=0.50
- 9.Up or Down Shell Plated:Nickel 80u" Plated Over Cu 50u"
- 10.Connector Shell Material: SPCC T=0.50
- 11.Connector Shell Plated: Gold 1~3u" Plated Over Cu 50u"
- 12.Hook Spring Material: Stainless Steel T=0.30



**Ordering Information**

**6320-M026 S D XX P N A O X**

No.of Pins  
14,20P,26P,36P  
50P

Connector Type  
S= Straight

Contact Plating  
G1:1U" Gold  
G4:3U" Gold  
G5:5U" Gold  
S1:1U" Gold /Tin  
S2:3U" Gold /Tin  
S3:5U" Gold /Tin

Stream Code

**JILN** 深圳市锦凌电子有限公司  
SHENZHEN JINLING ELECTRONICS CO.,LTD

Tel: 86-755-27483253 Fax: 86-755-2997-5588

PART NO.

6320-M026SDXXPNAX

TITLE:

HPCN 26P SCSI Solder-type Male

**OPERATION**

X.X	±0.30
X.XX	±0.20
X.XXX	±0.10
Angle	±3°
DIM	TOL

**DRAW**

Jelly Feng

**CHECK**

**APPROVE**

23.02.15

**SCALE**

UNIT

SIZE

SHEET

PROJ.

**FIT**

mm

A4

1/1

PROJ.

A0	2017.06.22	NEW DRAWING						
REV	DATE	MODIFICATION DESCRIPTION	CHANGE					